

## **General Description**

The WSD40L48DN is the highest performance trench P-ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSD40L48DN meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

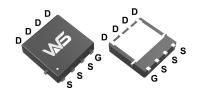
# **Product Summery**

BVDSS	RDSON	ID
-40V	16mΩ	-30A

# **Applications**

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

## **DFN3X3-8 Pin Configuration**





## **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-40	V
$V_{GS}$	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	-30	Α
I <sub>D</sub> @T <sub>C</sub> =100℃	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	-10	Α
I <sub>D</sub> @T <sub>A</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	-13	А
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	-8	Α
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	-75	А
EAS	Single Pulse Avalanche Energy <sup>3</sup>	49	mJ
I <sub>AS</sub>	Avalanche Current	-14	А
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	35	W
P <sub>D</sub> @T <sub>A</sub> =25℃	Total Power Dissipation <sup>4</sup>	3.1	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	℃
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

#### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>		50	°C/W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹ (t ≤10s)		40	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>		3.5	°C/W



# Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-40			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25℃ , I <sub>D</sub> =-1mA		-0.022		V/℃
D	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V , I <sub>D</sub> =-15A		16	24	<b>~~</b> 0
R <sub>DS(ON)</sub>		V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-10A		20	30	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	-V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-1.3	-1.9	-2.5	٧
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	V <sub>GS</sub> -V <sub>DS</sub> , I <sub>D</sub> 250uA		4.6		mV/℃
l	Drain-Source Leakage Current	V <sub>DS</sub> =-32V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃			-1	uA
I <sub>DSS</sub>	Dialii-Source Leakage Current	$V_{DS}$ =-32V , $V_{GS}$ =0V , $T_J$ =55 $^{\circ}$ C			-5	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm 20V$ , $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =-5V , I <sub>D</sub> =-15A	30			S
$R_g$	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		2.1		Ω
$Q_g$	Total Gate Charge (-4.5V)	V <sub>DS</sub> =-15V , V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-15A		33		
$Q_gs$	Gate-Source Charge			5.5		nC
$Q_gd$	Gate-Drain Charge			8.3		
T <sub>d(on)</sub>	Turn-On Delay Time			15		
T <sub>r</sub>	Rise Time	V <sub>DD</sub> =-20V , V <sub>GS</sub> =-10V ,		13		20
T <sub>d(off)</sub>	Turn-Off Delay Time	$R_G$ =6Ω, $I_D$ =-1A, $RL$ =20Ω.		42		ns
T <sub>f</sub>	Fall Time			23		
Ciss	Input Capacitance	V <sub>DS</sub> =-20V , V <sub>GS</sub> =0V , f=1MHz		1760		
C <sub>oss</sub>	Output Capacitance			228		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			185		

#### **Guaranteed Avalanche Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy <sup>5</sup>	V <sub>DD</sub> =-25V , L=0.5mH , I <sub>AS</sub> =-14A	38			mJ

## **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			-20	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>				-80	Α
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}$ =0V , $I_{S}$ =-10A , $T_{J}$ =25 $^{\circ}$ C		0.74	-1.2	V
t <sub>rr</sub>	Reverse Recovery Time	lF=-10A,dI/dt=100A/μs , Tյ=25℃		20		nS
Q <sub>rr</sub>	Reverse Recovery Charge			18		nC

#### Note:

- 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, t<10sec.
- 2.The data tested by pulsed , pulse width  $\,\leq\,300\text{us}$  , duty cycle  $\,\leq\,2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}$ =-25V, $V_{GS}$ =-10V,L=0.5mH,I<sub>AS</sub>=-14A
- 5.The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



# **Typical Characteristics**

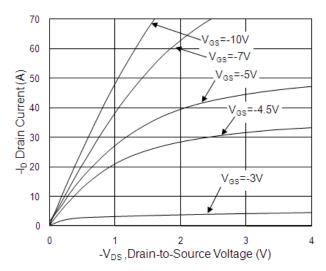


Fig.1 Typical Output Characteristics

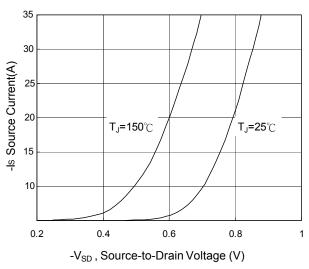


Fig.3 Forward Characteristics of Reverse

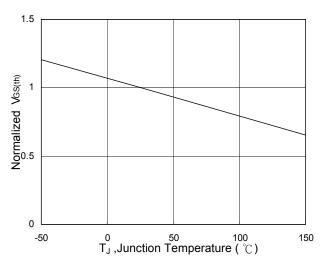


Fig.5 Normalized  $V_{\text{GS(th)}}$  vs.  $T_J$ 

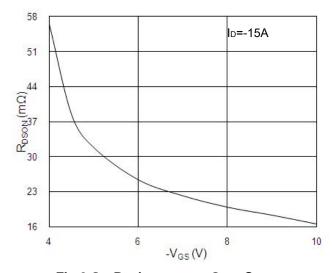


Fig.2 On-Resistance v.s Gate-Source

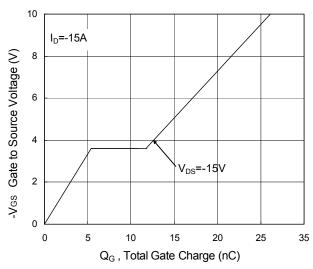


Fig.4 Gate-Charge Characteristics

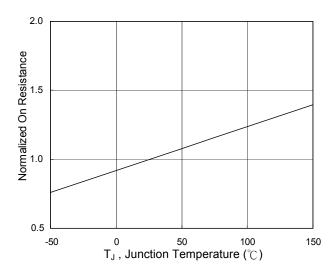
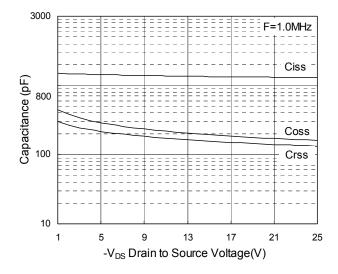


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>





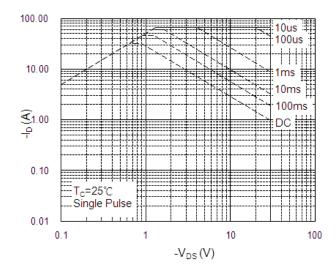


Fig.7 Capacitance

Fig.8 Safe Operating Area

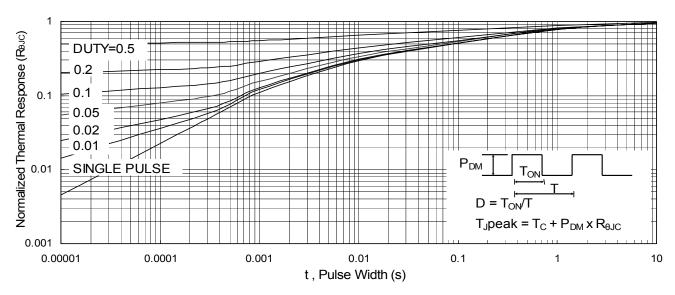


Fig.9 Normalized Maximum Transient Thermal Impedance

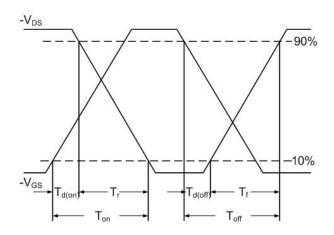


Fig.10 Switching Time Waveform

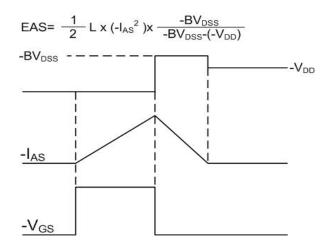


Fig.11 Unclamped Inductive Switching Waveform



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